

# EMK32H2J-7.340032M TR [Click part number to visit Part Number Details page](#)

## REGULATORY COMPLIANCE (Data Sheet downloaded on Apr 22, 2017)



◀ Click badges to download compliance docs

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.



## ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 2.5Vdc 4 Pad 2.5mm x 3.2mm Plastic Surface Mount (SMD) 7.340032MHz  $\pm$ 50ppm over -40°C to +85°C

## ELECTRICAL SPECIFICATIONS

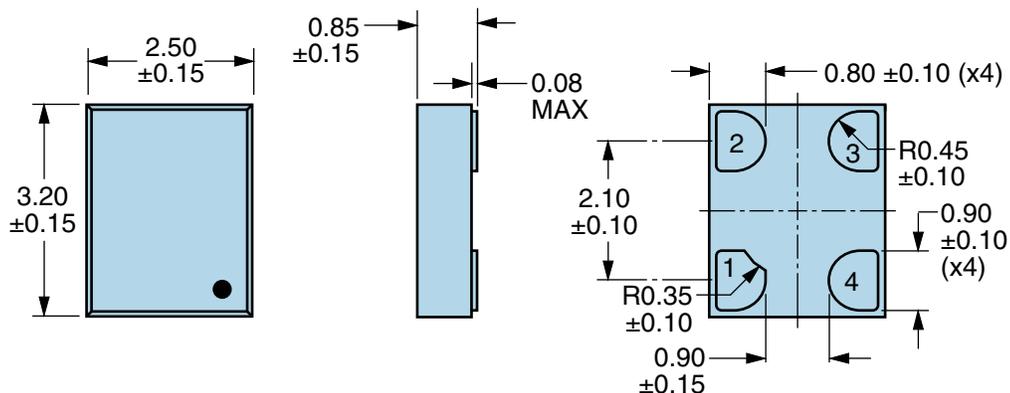
Nominal Frequency	7.340032MHz
Frequency Tolerance/Stability	$\pm$ 50ppm Maximum over -40°C to +85°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, 260°C Reflow, Shock, and Vibration)
Aging at 25°C	$\pm$ 1ppm Maximum First Year
Supply Voltage	2.5Vdc $\pm$ 5%
Input Current	17mA Maximum
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH=-8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL=+8mA)
Rise/Fall Time	2nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 $\pm$ 5(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Power Down (Disabled Output: Logic Low)
Output Control Input Voltage	+0.7Vdd Minimum or No Connect to Enable Output, +0.3Vdd Maximum to Disable Output
Standby Current	50 $\mu$ A Maximum (Disabled Output: Logic Low)
Peak to Peak Jitter (tPK)	500pSec Maximum, 200pSec Typical
Start Up Time	50mSec Maximum
Storage Temperature Range	-55°C to +125°C

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Pads on Bottom of Package Only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

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## MECHANICAL DIMENSIONS (all dimensions in millimeters)

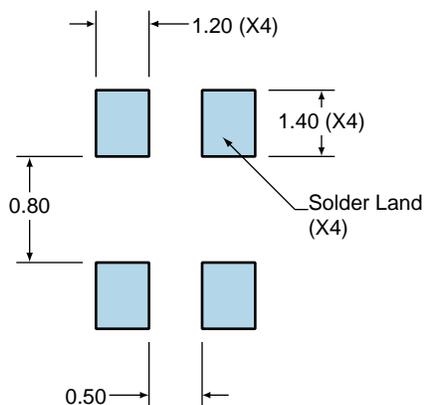


PIN	CONNECTION
1	Power Down
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Lot Code

## Suggested Solder Pad Layout

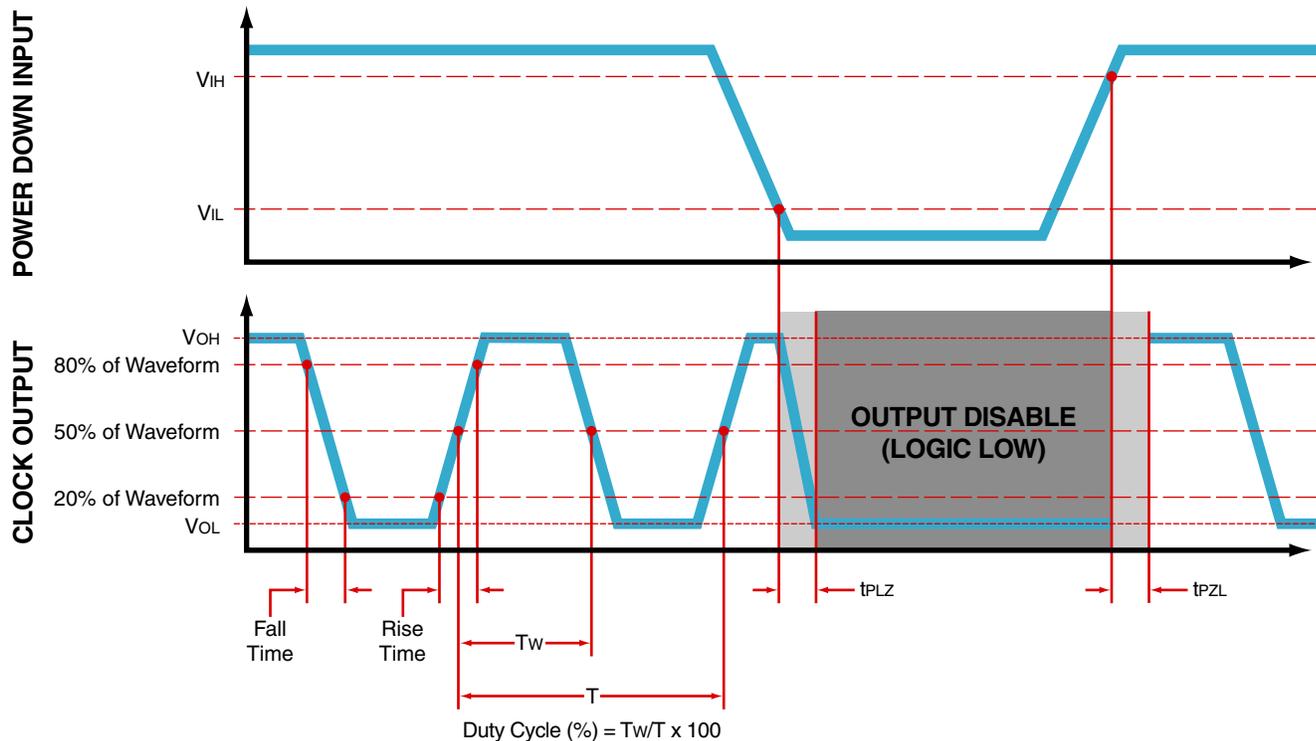
All Dimensions in Millimeters



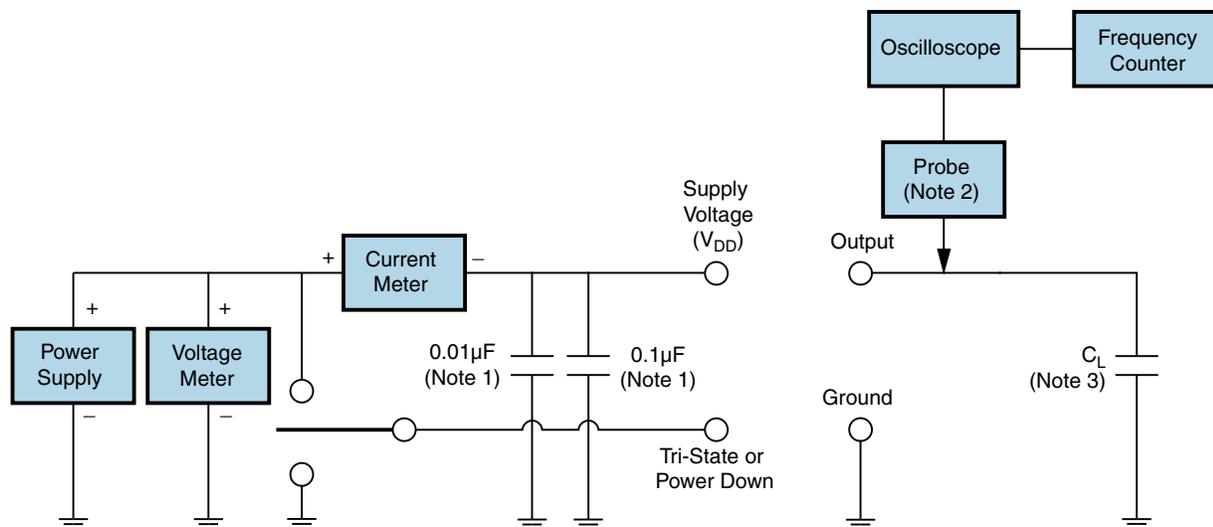
All Tolerances are  $\pm 0.1$

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## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for CMOS Output



Note 1: An external  $0.01\mu\text{F}$  ceramic bypass capacitor in parallel with a  $0.1\mu\text{F}$  high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low input capacitance ( $<12\text{pF}$ ), 10X Attenuation Factor, High Impedance ( $>10\text{Mohms}$ ), and High bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

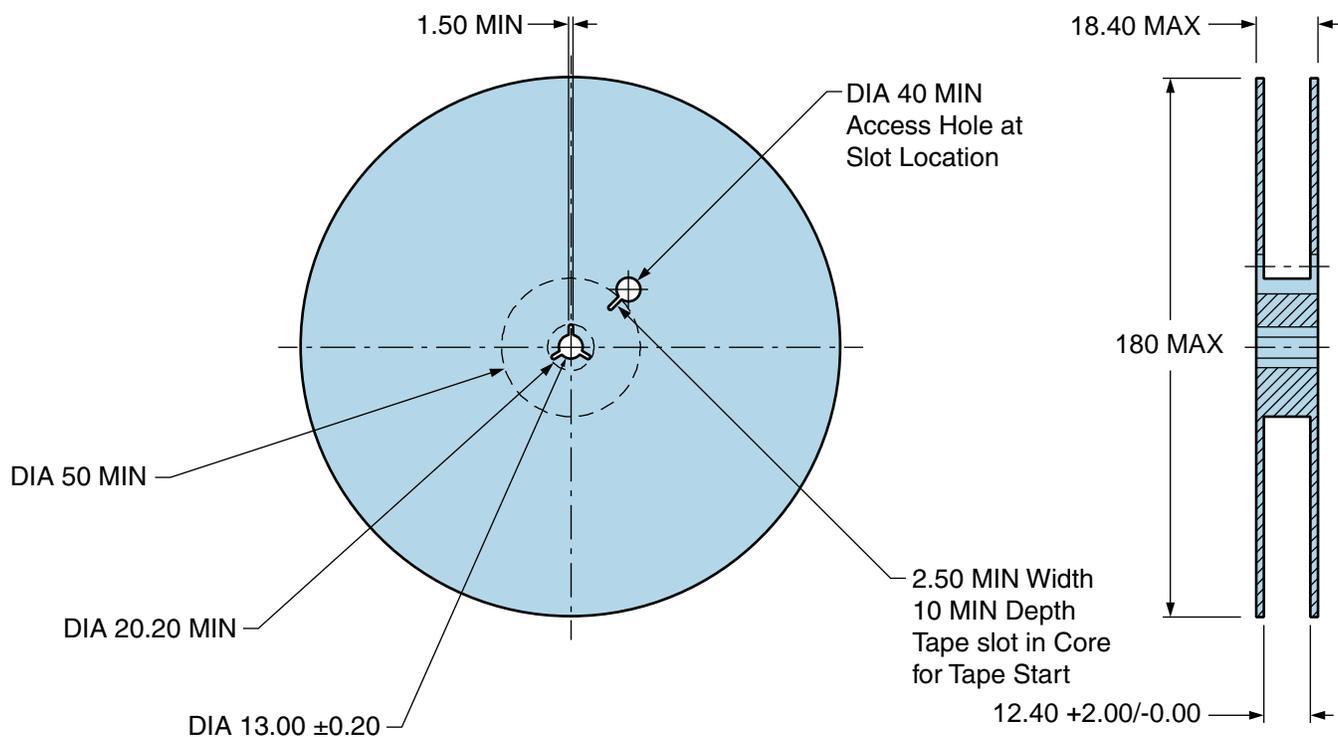
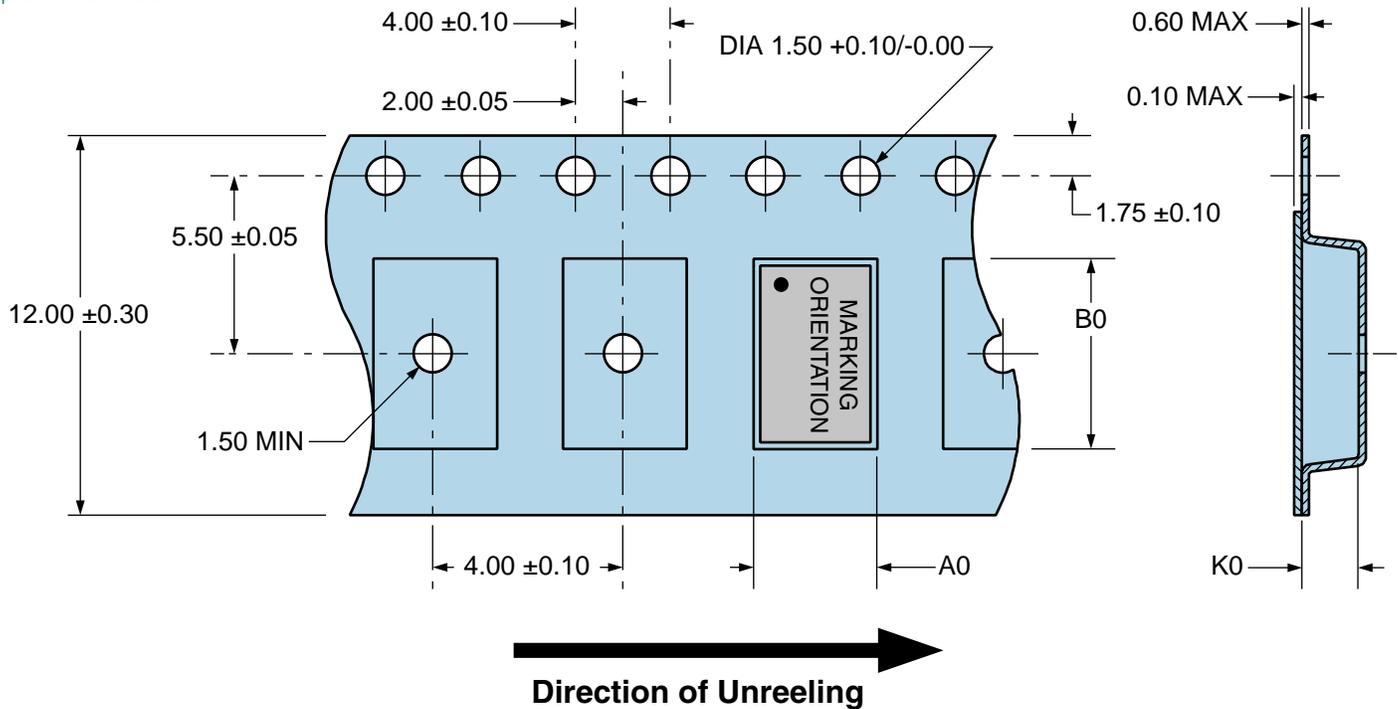
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## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

Compliant to EIA-481



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## Recommended Solder Reflow Methods



### High Temperature Infrared/Convection

Ts MAX to TL (Ramp-up Rate)	3°C/Second Maximum
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#### Preheat

- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (TL to TP)	3°C/Second Maximum
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#### Time Maintained Above:

- Temperature (TL)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (TP)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (TP Target)	250°C +0/-5°C
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Time within 5°C of actual peak (tp)	20 - 40 Seconds
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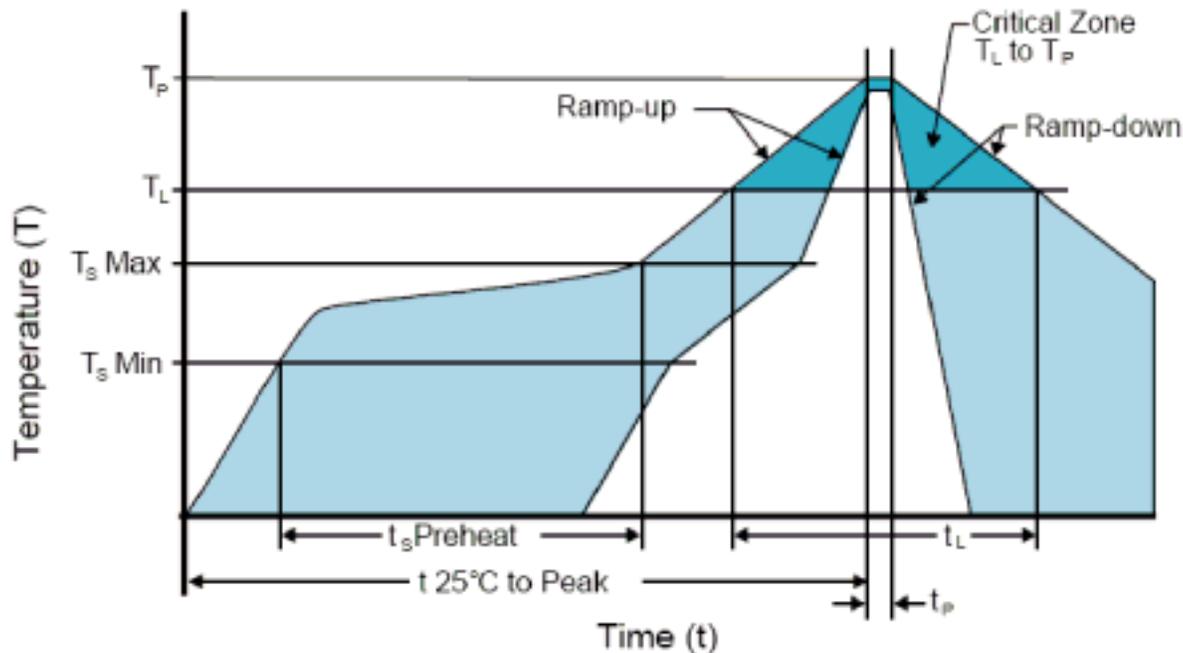
Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate) 5°C/Second Maximum

#### Preheat

- Temperature Minimum (Ts MIN) N/A  
 - Temperature Typical (Ts TYP) 150°C  
 - Temperature Maximum (Ts MAX) N/A  
 - Time (ts MIN) 60 - 120 Seconds

Ramp-up Rate (TL to TP) 5°C/Second Maximum

#### Time Maintained Above:

- Temperature (TL) 150°C  
 - Time (tL) 200 Seconds Maximum

Peak Temperature (TP) 240°C Maximum

Target Peak Temperature (TP Target) 240°C Maximum 2 Times / 230°C Maximum 1 Time

Time within 5°C of actual peak (tp) 10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time

Ramp-down Rate 5°C/Second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.